



WANSEMI
万芯半导体

WP2060AP3

Enhancement Mode N-Channel Power MOSFET

PDFN3x3/NMOS/20V/ ± 12 V/0.85V/60A/3.4m Ω

Rev0.6

20V, 3.4mΩ, 60A, Single N-Channel

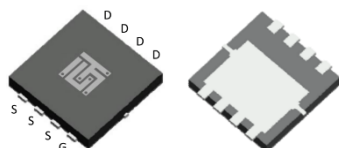
1.Features

- ◆ 20V MOSFET technology
- ◆ Low on-state resistance
- ◆ Fast switching
- ◆ $V_{GS} \pm 12V$

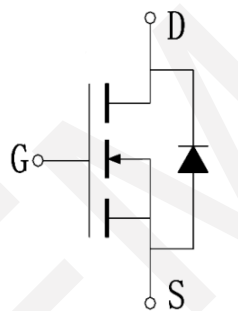
V_{DS}	$R_{DS(on)}$ Typ.	I_D Max.
20V	3.4mΩ @ 4.5V	60A
	4.6mΩ @ 2.5V	

2.Applications

- ◆ Power Switching Application
- ◆ Load Switching



PDFN3x3
Pin Description



Schematic Diagram

3.Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Tube	PCS/CTN.
WP2060AP3	WP2060AP3	PDF3x3	5,000	50,000

4.Absolute Max Ratings at Ta=25°C (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	V_{DSS}	20	V
Gate to Source Voltage	V_{GSS}	± 12	V
Drain Current (DC)	I_D	60	A
Drain Current (Pulse), $PW \leq 300\mu s$	I_{DP}	240	A
Total Dissipation	P_D	39	W
Avalanche Energy, Single Pulsed	E_{AS}	121	mJ
Junction Temperature	T_J	150	°C
Storage Temperature	T_{stg}	-55 to +150	°C

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

5. Thermal Resistance Ratings

Parameter	Symbol	Value	Unit
Junction to case	$R_{\theta JC}$	3.2	$^{\circ}\text{C/W}$

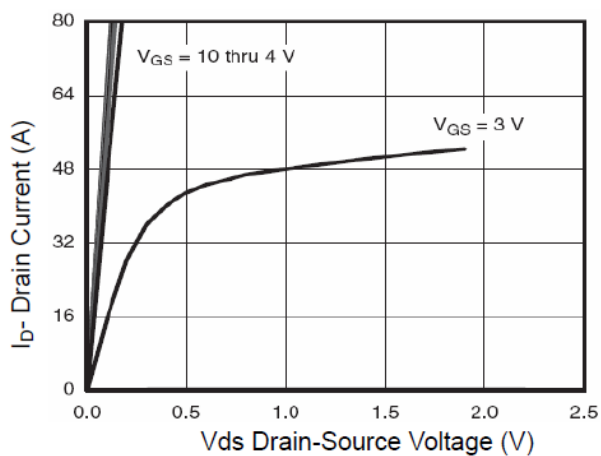
Note 2: When mounted on 1 inch square copper board $t \leq 10\text{sec}$ The value in any given application depends on the user's specific board design.

6. Electrical Characteristics at $T_a=25^{\circ}\text{C}$ (Note 3)

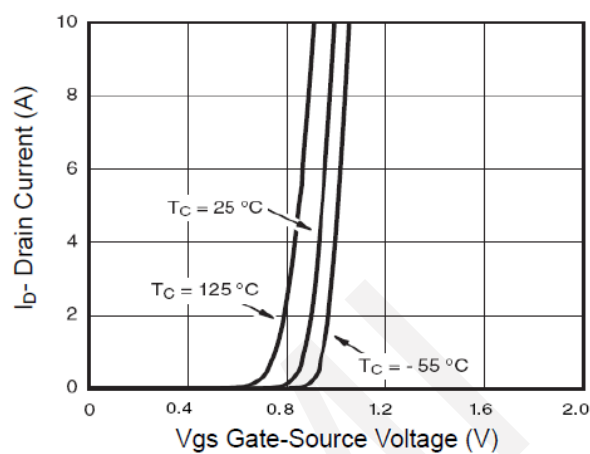
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$	20			V
Zero-Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20\text{V}$, $V_{GS} = 0\text{V}$			1	μA
Gate to Source Leakage Current	I_{GSS}	$V_{GS} = \pm 12\text{V}$, $V_{DS} = 0\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{DS}=250\mu\text{A}$	0.5	0.85	1.0	V
Static Drain to Source On-State Resistance	$R_{DS(on)}$	$I_D = 30\text{A}$, $V_{GS} = 4.5\text{V}$	-	3.4	4	$\text{m}\Omega$
		$I_D = 20\text{A}$, $V_{GS} = 2.5\text{V}$	-	4.6	6	$\text{m}\Omega$
Forward Transconductance	G_{FS}	$I_D = 30\text{A}$, $V_{DS} = 10\text{V}$	15			S
Input Capacitance	C_{iss}	$V_{GS}=0\text{V}$, $V_{DS}=10\text{V}$, Frequency=1.0MHz		3476		pF
Output Capacitance	C_{oss}			528		pF
Reverse Transfer Capacitance	C_{rss}			464		pF
Turn-ON Delay Time	$t_{d(on)}$	$V_{DD} = 10\text{V}$, $I_D = 30\text{A}$, $V_{GS} = 4.5\text{V}$, $R_G = 3\Omega$,		8		ns
Rise Time	t_r			19		ns
Turn-OFF Delay Time	$t_{d(off)}$			73		ns
Fall Time	t_f			80		ns
Total Gate Charge	Q_g	$V_{DS} = 10\text{V}$, $V_{GS} = 8\text{V}$, $I_D = 30\text{A}$		65		nC
	Q_{gs}			8		nC
	Q_{gd}			12		nC
Diode Forward Voltage	V_{FSD}	$I_S = 30\text{A}$, $V_{GS} = 0\text{V}$		0.8	1.2	V

Note 3: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

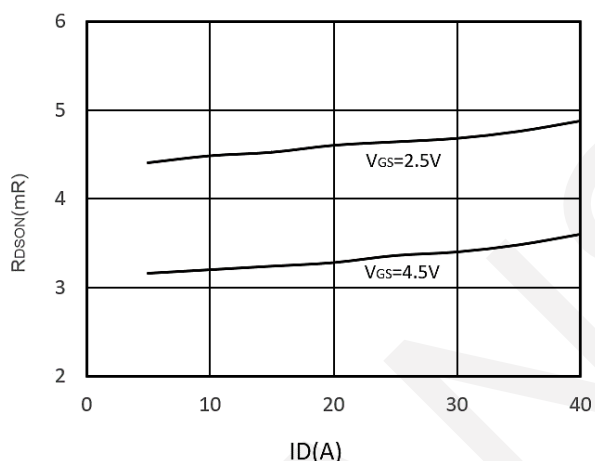
7. Typical electrical and thermal characteristics



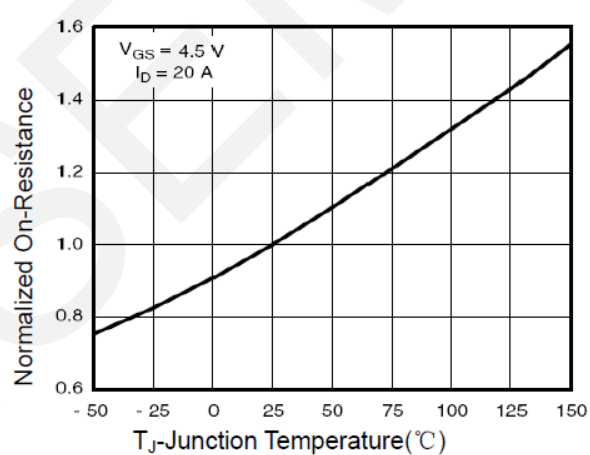
Output Characteristics



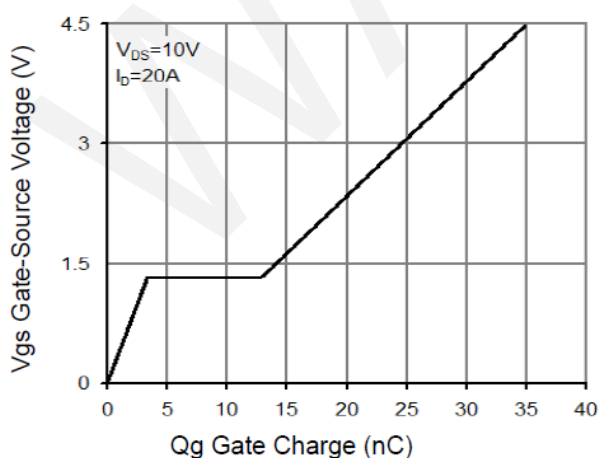
Transfer Characteristics



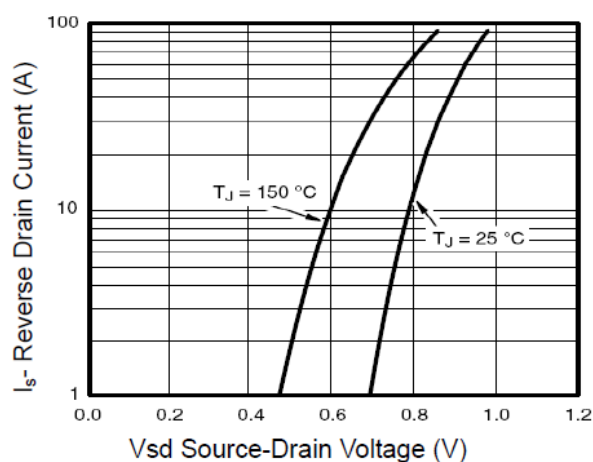
$R_{DS(on)}$ -Drain Current



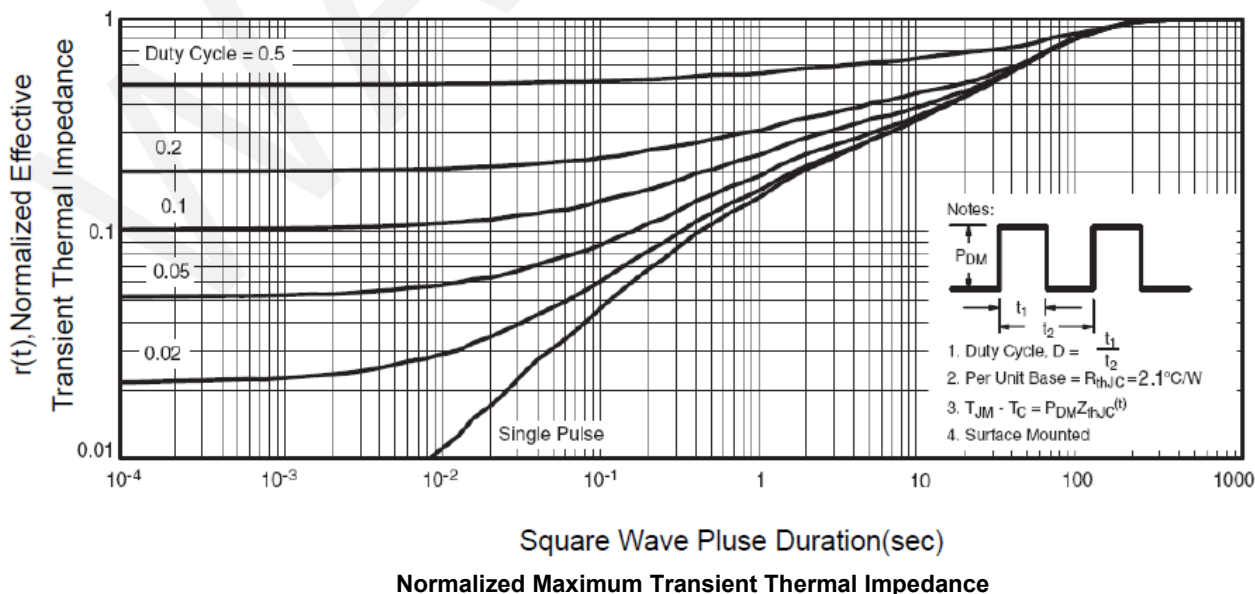
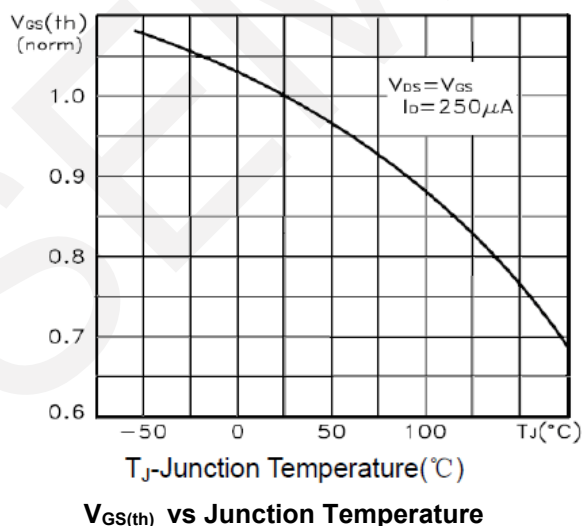
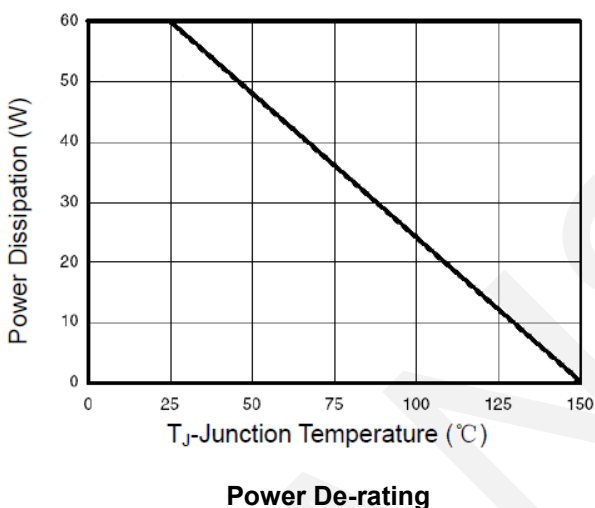
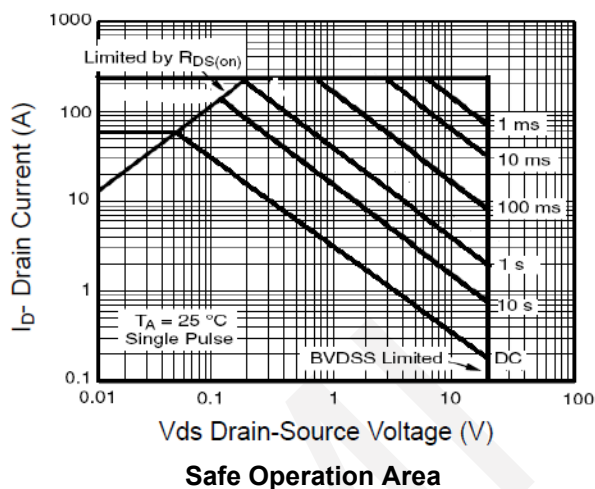
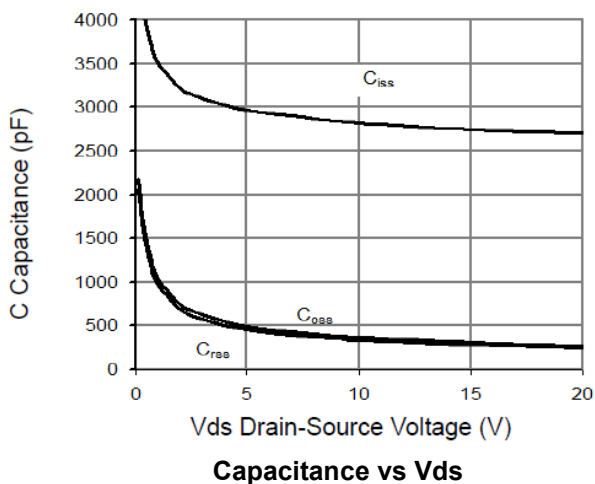
$R_{DS(on)}$ -Junction Temperature



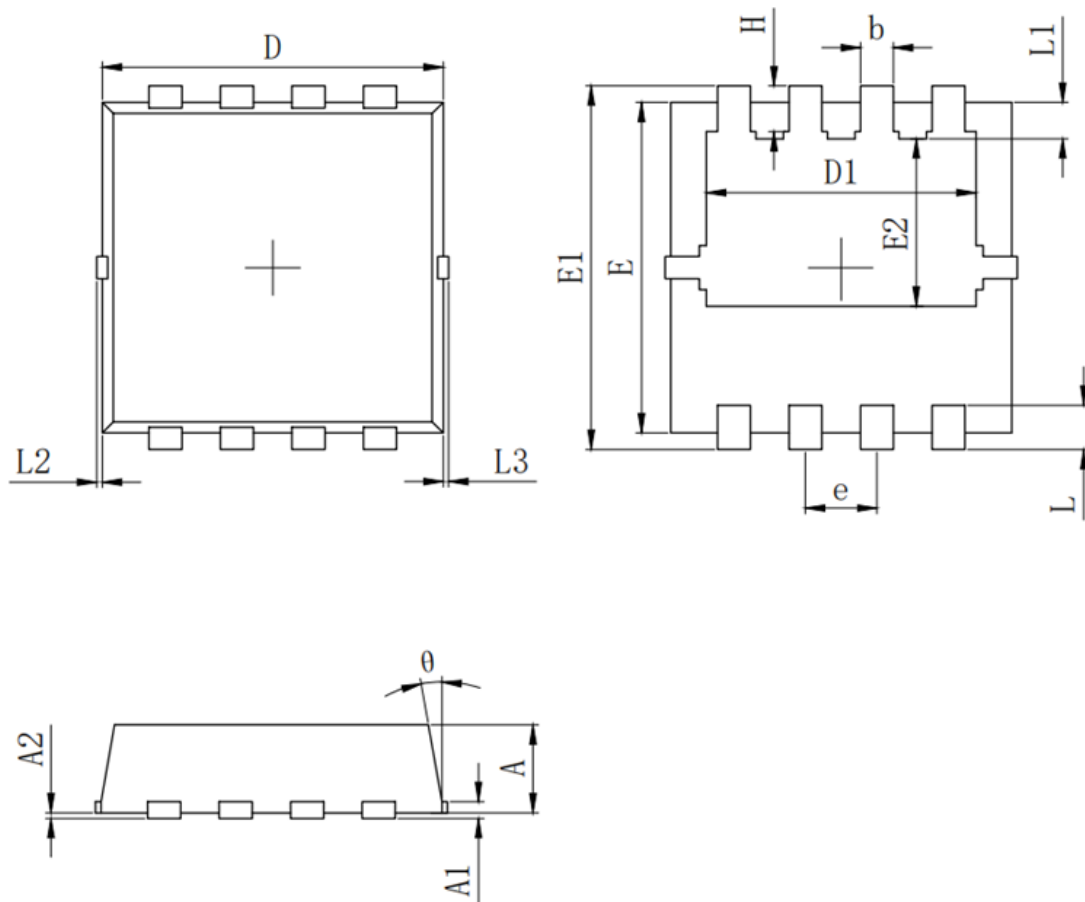
Gate Charge



Source-Drain Diode Forward



8.Package Dimensions



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.700	0.800	0.900
A1	0.152 REF.		
A2	0~0.05		
D	3.000	3.100	3.200
D1	2.300	2.450	2.600
E	2.900	3.000	3.100
E1	3.150	3.300	3.450
E2	1.320	1.520	1.720
b	0.200	0.300	0.400
e	0.550	0.650	0.750
L	0.300	0.400	0.500
L1	0.180	0.330	0.480
L2	0~0.100		
L3	0~0.100		
H	0.315	0.415	0.515
θ	8°	10°	12°

9. Important Notice

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